

Filename: PMP8372_BOM.xls				
Date: 04/10/2014				
<b>PMP8372B_BOM</b>				
count	RefDes	value	Description	Size
1	C3	22uF	CAP ALUM 22UF 50V 20% RADIAL	6.30mm Dia
4	C7 C11 C18 C22	10uF	Capacitor, Ceramic Chip, 25V, X5R, ±10%	0805
6	C5-6 C10 C16-17	47uF	Capacitor, Ceramic Chip, 25V, X5R, ±20%	1206
1	C20	0.01uF	Capacitor, Ceramic Chip, 25V, X7R, ±10%	0603
2	C8-20 C19	1uF	Capacitor, Ceramic Chip, 25V, X7R, ±10%	0603
1	C23	2.2uF	Capacitor, Ceramic Chip, 50V, X5R, ±10%	0805
4	C1-2 C12-13	4.7uF	Capacitor, Ceramic Chip, 50V, X5R, ±10%	0805
0	C4 C15	DNP	Capacitor, Ceramic Chip, 50V, X7R, ±10%	0603
1	D1	DDZ9689	DIODE ZENER 5.1V 500MW SOD123	SOD-123
1	U4	TPS7A3301RGW	IC, 36V 1A, Ultralow-Noise Negative Voltage Regulator	QFN
1	U3	TPS84259RKG	IC, 4.5-V to 40-V Input, 2-A, Negative Output, Integrated Power Solution	QFN
1	U1	TPS84250RKG	IC, 7-50 V Input, 2.5-A Non-synchronous Buck,	QFN
1	U2	TPS7A4701RGWR	IC, Low Noise Power Solution For High Performance Signal Chain Applications	QFN-20
1	R7	1.1M	Resistor, Chip, 1/16W, 1%	0603
1	R8	100k	Resistor, Chip, 1/16W, 1%	0603
1	R16	102k	Resistor, Chip, 1/16W, 1%	0603
2	R1 R9	174k	Resistor, Chip, 1/16W, 1%	0603
2	R2 R10	24.3k	Resistor, Chip, 1/16W, 1%	0603
1	R4	30.9k	Resistor, Chip, 1/16W, 1%	0603
1	R15	332k	Resistor, Chip, 1/16W, 1%	0603
2	R5 R11	49.9	Resistor, Chip, 1/16W, 1%	0603
1	R3	49.9k	Resistor, Chip, 1/16W, 1%	0603
1	R6	62k	Resistor, Chip, 1/16W, 1%	0603
1	R13	64.9k	RES 64.9K OHM 1/10W 1% 0603 SMD	0603
5	J1 J4 J6 J8 J10	ED555/2DS	Terminal Block, 2-pin, 6-A, 3.5mm	0.27 x 0.25 inch
6	TP2 TP8 TP10 TP12 TP18 TP20	5011	Test Point, Black, Thru Hole	0.125 x 0.125 inch



Count	RefDes	Manufacturer Part	MFR	Digi-Key PN
1	C3	ECE-A1HKA220	Panasonic Electronic Components	445-14387-2-ND
4	C7 C11 C18 C22	C2012X5R1E106K0	TDK Corporation	445-14387-1-ND
6	C5-6 C10 C16-17 C	C3216X5R1E476M1	TDK Corporation	445-8047-1-ND
1	C20	C1608X7R1E104K0	TDK Corporation	445-1316-1-ND
2	C8-20 C19	C1608X5R1E105K0	TDK Corporation	445-5146-1-ND
1	C23	C2012X5R1H225K1	TDK Corporation	445-5976-1-ND
4	C1-2 C12-13	C2012X5R1H475K1	TDK Corporation	445-5980-1-ND
0	C4 C15	STD	STD	
1	D1	DDZ9687-7	Diodes Incorporated	DDZ9687-7DICT-ND
1	U4	TPS7A3301RGW	TI	296-34830-1-ND
1	U3	TPS84259RKG	TI	296-34945-1-ND
1	U1	TPS84250RKG	TI	296-34969-1-ND
1	U2	TPS7A4701RGWR	TI	296-37224-1-ND
1	R7	ERJ-3EKF1104V	Panasonic Electronic Components	P1.10MHCT-ND
1	R8	5-1879338-6	TE Connectivity	A102199CT-ND
1	R16	5-1879338-7	TE Connectivity	A102201CT-ND
2	R1 R9	RP73PF1J174KBTDF	TE Connectivity	A110323CT-ND
2	R2 R10	RP73PF1J24K3BTDF	TE Connectivity	A110241CT-ND
1	R4	RP73PF1J30K9BTDF	TE Connectivity	A110251CT-ND
1	R15	RP73PF1J332KBTDF	TE Connectivity	A110350CT-ND
2	R5 R11	3-1879335-6	TE Connectivity	A102283CT-ND
1	R3	2-1879338-7	TE Connectivity	A102282CT-ND
1	R6	A103118CT-ND	TE Connectivity	A103118CT-ND
1	R13	RC0603FR-0764K9	Yageo	311-64.9KHRCT-ND
5	J1 J4 J6 J8 J10	ED555/2DS	On Shore Technology Inc	ED1514-ND
6	TP2 TP8 TP10 TP12 TP18 TP20	5011	Keystone	5011K-ND
7	TP3-6 TP13 TP15-16	5013	Keystone	5013K-ND
6	TP1 TP7 TP9 TP11 TP17 TP19	5010	Keystone	5010K-ND
1	Q1	EMD12T2R	Rohm Semiconductor	EMD12T2RCT-ND

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